

40V PNP SMALL SIGNAL SURFACE MOUNT TRANSISTOR

Features

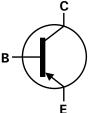
- Complementary NPN Type Available (MMBT3904LP)
- Ultra-Small Leadless Surface Mount Package
- "Lead Free", RoHS Compliant (Note 1)
- Halogen and Antimony Free. "Green" Device (Note 2)
- ESD rating: 200V-MM, 4KV-HBM

Mechanical Data

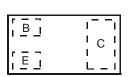
- Case: DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.008 grams (approximate)



Bottom View



Device Symbol



Top View Device Schematic

Ordering Information

Notes:

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
MMBT3906LP-7	3N	7	8mm	3,000
MMBT3906LP-7B	3N	7	8mm	10,000

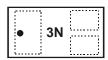
1. No purposefully added lead.

2. Diodes Inc's "Green" policy can be found on our website at http://www.diodes.com.

3. For packaging details, go to our website at http://www.diodes.com.

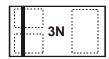
Marking Information

MMBT3906LP-7



Top View Dot Denotes Collector Side

MMBT3906LP-7B



Top View Bar Denotes Base and Emitter Side 3N = Product Type Marking Code



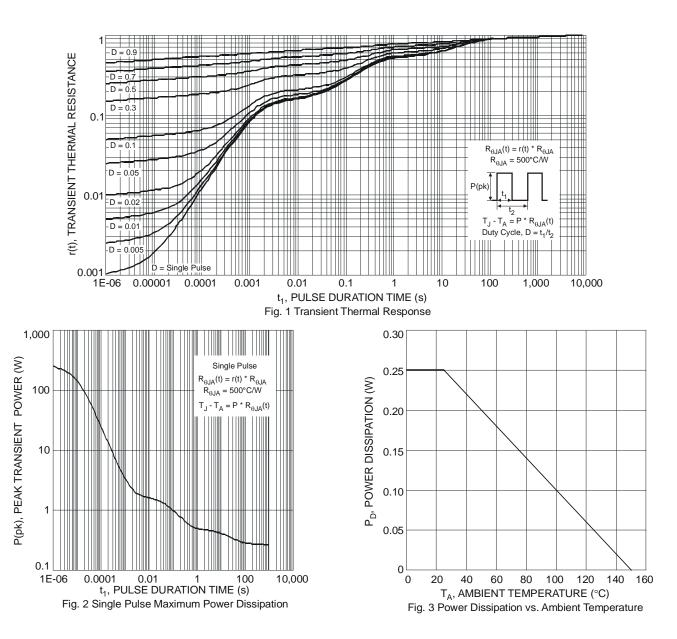
Maximum Ratings $@T_A = 25^{\circ}C$ unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-40	V
Collector-Emitter Voltage	V _{CEO}	-40	V
Emitter-Base Voltage	V _{EBO}	-5.0	V
Collector Current - Continuous (Note 4)	Ι _C	-200	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 4)	PD	250	mW
Thermal Resistance, Junction to Ambient (Note 4)	$R_{ heta JA}$	500	°C/W
Operating and Storage and Temperature Range	TJ, TSTG	-55 to +150	۵°

Notes: 4. Device mounted on FR-4 PCB, pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com

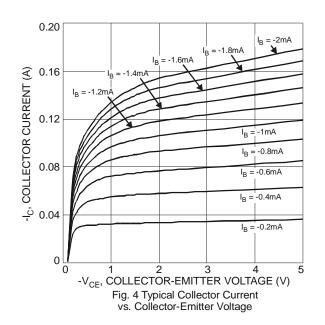


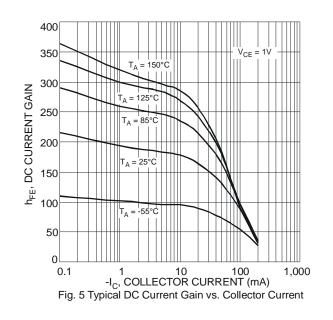


Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition	
DFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	BV _{CBO}	-40	_	V	$I_{\rm C} = -10 \mu A, I_{\rm E} = 0$	
Collector-Emitter Breakdown Voltage (Note 5)	BV _{CEO}	-40	_	V	$I_{\rm C} = -1.0 {\rm mA}, I_{\rm B} = 0$	
Emitter-Base Breakdown Voltage	BV _{EBO}	-5.0	—	V	$I_{E} = -10\mu A, I_{C} = 0$	
Collector Cutoff Current	I _{CEX}	_	-50	nA	$V_{CE} = -30V, V_{EB(OFF)} = -3.0V$	
	ICBO		-50	nA	$V_{CB} = -30V, I_E = 0$	
Base Cutoff Current	I _{BL}	_	-50	nA	$V_{CE} = -30V, V_{EB(OFF)} = -3.0V$	
ON CHARACTERISTICS (Note 5)			•	1	1	
		60	—		$I_{C} = -100\mu A, V_{CE} = -1.0V$ $I_{C} = -1.0mA, V_{CE} = -1.0V$	
DC Current Gain	b	80 100	300		$I_{C} = -1.0 \text{mA}, V_{CE} = -1.0 \text{V}$ $I_{C} = -10 \text{mA}, V_{CE} = -1.0 \text{V}$	
	h _{FE}	60	500		$I_{C} = -50 \text{mA}, V_{CE} = -1.0 \text{V}$	
		30	_		$I_{\rm C} = -100$ mA, $V_{\rm CE} = -1.0$ V	
			-0.25		$I_{\rm C} = -10$ mA, $I_{\rm B} = -1.0$ mA	
Collector-Emitter Saturation Voltage	V _{CE(sat)}	—	-0.40	V	$I_{\rm C} = -50$ mA, $I_{\rm B} = -5.0$ mA	
Base-Emitter Saturation Voltage		-0.65	-0.85	V	$I_{\rm C} = -10 {\rm mA}, I_{\rm B} = -1.0 {\rm mA}$	
Base-Emiller Saluration Voltage	V _{BE(sat)}	_	-0.95		I _C = -50mA, I _B = -5.0mA	
SMALL SIGNAL CHARACTERISTICS						
Output Capacitance	C _{obo}	_	4.5	pF	$V_{CB} = -5.0V$, f = 1.0MHz, I _E = 0	
Input Capacitance	Cibo	_	10	pF	$V_{EB} = -0.5V, f = 1.0MHz, I_C = 0$	
Input Impedance	h _{ie}	2.0	12	kΩ		
Voltage Feedback Ratio	h _{re}	0.1	10	x 10 ⁻⁴	$V_{CE} = 10V, I_C = 1.0mA,$	
Small Signal Current Gain	h _{fe}	100	400	_	f = 1.0kHz	
Output Admittance	h _{oe}	3.0	60	μS		
Current Gain-Bandwidth Product	f⊤	300	—	MHz	$V_{CE} = -20V, I_C = -10mA,$ f = 100MHz	
SWITCHING CHARACTERISTICS						
Delay Time	t _d	_	35	ns	$V_{CC} = -3.0V, I_{C} = -10mA,$	
Rise Time	tr	_	35	ns	$V_{BE(off)} = 0.5V, I_{B1} = -1.0mA$	
Storage Time	ts	_	225	ns	$V_{CC} = -3.0V, I_C = -10mA,$	
Fall Time	t _f		75	ns	$I_{B1} = I_{B2} = -1.0 \text{mA}$	

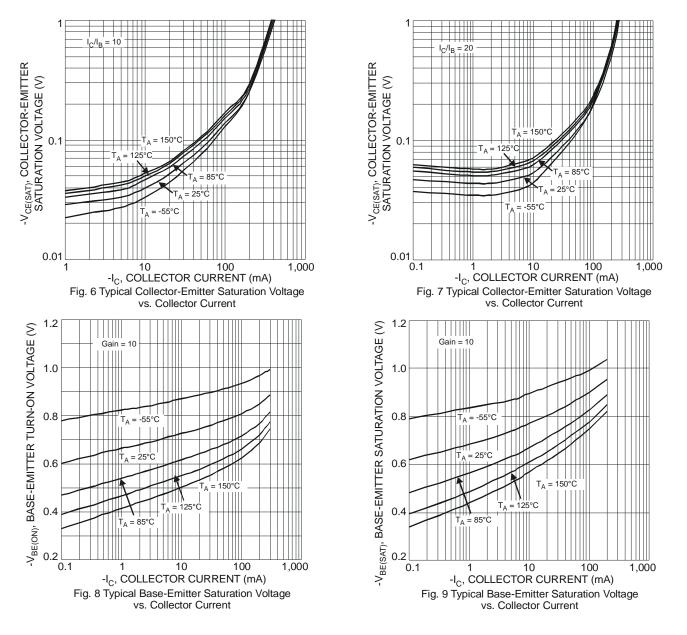
Notes: 5. Short duration pulse test used to minimize self-heating effect.



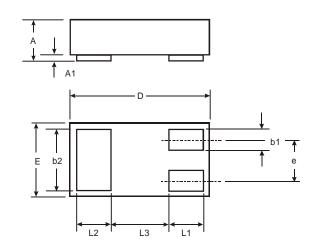




MMBT3906LP



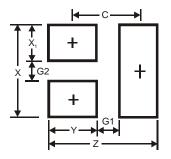
Package Outline Dimensions



DFN1006-3				
Dim	Min	Max	Тур	
Α	0.47	0.53	0.50	
A1	0	0.05	0.03	
b1	0.10	0.20	0.15	
b2	0.45	0.55	0.50	
D	0.95	1.075	1.00	
Е	0.55	0.675	0.60	
е		_	0.35	
L1	0.20	0.30	0.25	
L2	0.20	0.30	0.25	
L3	_	_	0.40	
All Dimensions in mm				



Suggested Pad Layout



Dimensions	Value (in mm)
Z	1.1
G1	0.3
G2	0.2
Х	0.7
X1	0.25
Y	0.4
С	0.7

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